

# isola

## I-Tera<sup>®</sup> MT40 (RF/MW)

### Very Low-Loss Laminate Material

I-Tera<sup>®</sup> MT40 laminate materials exhibit exceptional electrical properties which are very stable over a broad frequency and temperature range.

I-Tera MT40 is suitable for many of today's high speed digital and RF/microwave printed circuit designs. I-Tera MT40 features a dielectric constant (Dk) that is stable between -40°C and +140°C up to W-band frequencies. In addition, I-Tera MT40 offers a very low dissipation factor (Df) of 0.0028 - 0.0035 making it a cost effective alternative to PTFE and other commercial microwave and high-speed digital laminate materials.

I-Tera MT40 laminate materials are currently being offered in both laminate and prepreg form in typical thicknesses and standard panel sizes. This provides a complete materials solution package for high-speed digital multilayer, hybrid, RF/microwave, multilayer and double-sided printed circuit designs. I-Tera MT40 does not require any special through hole treatments commonly needed when processing PTFE-based laminate materials.

### Product Attributes

RF/Microwave , High Thermal Reliability

### Typical Market Applications

Aerospace & Defense , Automotive & Transportation , Medical, Industrial & Instrumentation , RF / Microwave

RF/Microwave

## Data Sheet

Tg 200°C

Td 360°C

Dk 3.38 / 3.45 / 3.60 / 3.75

Df 0.0028 - 0.0035

IPC-4103/17

UL - File Number E41625

Last Updated December 7, 2017  
Revision No: 14

### Product Features

### Product Availability

Property	Typical Value	Units	Test Method	
		Metric (English)	IPC-TM-650 (or as noted)	
Glass Transition Temperature (Tg) by DSC	200	°C	2.4.25C	
Glass Transition Temperature (Tg) by TMA	205	°C	2.4.24C	
Decomposition Temperature (Td) by TGA @ 5% weight loss	360	°C	2.4.24.6	
Time to Delaminate by TMA (Copper removed)	A. T260 B. T288	>60	Minutes	2.4.24.1
Z-Axis CTE	A. Pre-Tg B. Post-Tg C. 50 to 260°C, (Total Expansion)	55 290 2.8	ppm/°C ppm/°C %	2.4.24C
X/Y-Axis CTE	Pre-Tg	12	ppm/°C	2.4.24C
Thermal Conductivity		0.61	W/mK	ASTM E1952
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched B. Etched	Pass	Pass Visual	2.4.13.1
Dk, Permittivity	A. @ 10 GHz B. @ 10 GHz C. @ 10 GHz D. @ 10 GHz	3.38 3.45 3.60 3.75	—	2.5.5.5
Df, Loss Tangent	A. @ 10 GHz B. @ 10 GHz C. @ 10 GHz D. @ 10 GHz	0.0028 0.0031 0.0035 0.0035	—	Bereskin Stripline
Volume Resistivity	C-96/35/90	1.33 x 10 <sup>7</sup>	MΩ-cm	2.5.17.1
Surface Resistivity	C-96/35/90	1.33 x 10 <sup>5</sup>	MΩ	2.5.17.1
Dielectric Breakdown		45.4	kV	2.5.6B
Arc Resistance		139	Seconds	2.5.1B
Electric Strength (Laminate & laminated prepreg)		45 (1133)	kV/mm (V/mil)	2.5.6.2A
Comparative Tracking Index (CTI)		3 (175-249)	Class (Volts)	UL 746A ASTM D3638
Peel Strength	1 oz. EDC foil	1.0 (5.7)	N/mm (lb/inch)	2.4.8C
Flexural Strength	A. Length direction B. Cross direction	71000 58000	ksi	2.4.4B
Tensile Strength	A. Length direction B. Cross direction	39000 35000	ksi	ASTM D3039
Poisson's Ratio	A. Length direction B. Cross direction	0.234 0.222	—	ASTM D3039
Moisture Absorption		0.1	%	2.6.2.1A
Flammability (Laminate & laminated prepreg)		V-0	Rating	UL 94
Max Operating Temperature		130	°C	UL 796

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

